

Data Center Energy Trends

- Data center electricity usage
 - □ Increased by 56% from 2005 to 2010
 - □ 1.1% to 1.5% total world electricity usage
 - 1.7% to 2.2% total US electricity

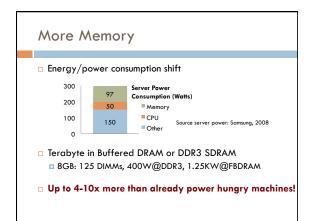
 (Note: Includes impact of 2008 recession.)

 (Note: 2x increase 2000 to 2005, below prediction.)

 Source: Koomey 2011

The Consequence At current growth rate (2000-2005) in energy usage for data centers, will need 30 new coal-fired or nuclear power plants by 2015 Matric Megatons CO₂ Matric Megatons CO₂ Matric Megatons CO₂ Matric Megatons CO₂ Argentina 170 Four-fold increase surposs airline industryl 178 178 146 Lacenters Source: Koomey 2011

Increasing Memory Demand Parallelism (core count) Larger & complex data sets More sophisticated applications Virtualization & consolidation Today: 10's (to 100's) GB Tomorrow: Terabyte and beyond??? Source: Kevin Te-Ming Lim, Disaggregated Microy Architectures for Blode Servers, Ph.D. Thesis, University of Michigan, 2010



DRAM A long-time winner: Decades old! Cost, power, performance trade-offs have favored it Massive future capacity leads to a different outcome! Limitations to DRAM Destructive reads: Must replace data after a read Limited data retention: Periodic refresh Susceptibility to errors: Charge can be disturbed Scalability: Projections (ITRS) question below 22nm

The Wave Rolling In

- □ DRAM has long been the best choice until now...
- □ DRAM **does** offer advantages
 - □ Effectively unlimited write endurance (doesn't wear out)
 - □ Fast read/write (symmetric) latency
 - □ (And, of course, it's a commodity, here today, etc.)
- □ Can we use it judiciously? Just a little bit, please?
 - □ Combine with alternative technology
 - Small DRAM has reasonable energy, capacity
 - We've seen this before... SRAM cache vs DRAM?

The Wave Rolling In JON STREET STREE

Alternative Memory Technology

| | Read Speed | Write Speed | Cell Area | Endurance | Addressability |
|------|------------|-------------|-----------------|------------------------------------|----------------|
| DRAM | 20~50ns | 20~50ns | 6F ² | 1015 | Yes |
| | ~2ns | ~2ns | | 10 ¹⁵ ~10 ¹⁶ | Yes |
| | 25us | 500us | | 104~105 | No |
| | 2ns | 10ns | | 1012 | Yes |
| PCM | 30~50ns | ~ 1 us | | 10 ⁷ ~10 ⁸ | Yes |

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Fast, non-destructive reads: Nearing parity w/DRAM Non-volatile, non-destructive, no refresh → low energy

Alternative Memory Technology

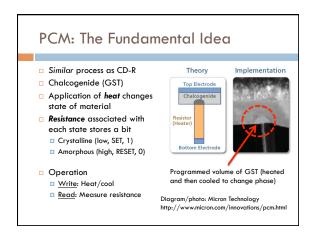
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Density on par with DRAM, 2.5nm prototype Liang et al, A 1.4uA Reset Current Phase Change Memory Cell with Integrated Carbon Nanotube Electrodes for Cross-Point Memory Applications, IEEE Symp. on VLSI (VLSII), 2011

Fast, non-destructive reads: Nearing parity w/DRAM

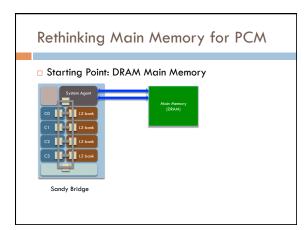
| Alte | rnative | Memo | ry Tec | hnolog | ΙΥ |
|-------------|--|----------------------|-----------------|----------------------------------|----------------|
| | Read Speed | Write Speed | Cell Area | Endurance | Addressability |
| DRAM | 20~50ns | 20~50ns | 6F ² | 10 ¹⁵ | Yes |
| SRAM | | ~2ns | | | Yes |
| NAND Flash | | 500us | | | No |
| STT-RAM | | 1 Ons | | | Yes |
| PCM | 30∼50ns | ~1 us | 5~8F2 | 10 ⁷ ~10 ⁸ | Yes |
| | Repeated writes Writes cause stres Limited write cycle | ss to bit cells, lea | ding to failure | | |
| Write perfo | rmance limited b | y individual bit | and group of | bits | |
| Densi | ty on par with DI | RAM, 2.5nm pro | totype | | |
| Fast, non- | destructive reads | s: Nearing parity | w/DRAM | | |

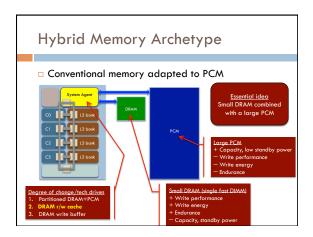
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|------------|-------------------------------------|-------------------|-----------------|------------------------------------|----------------|
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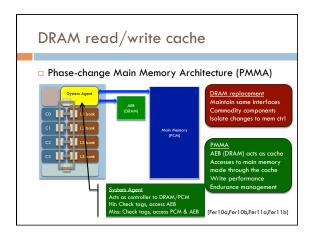


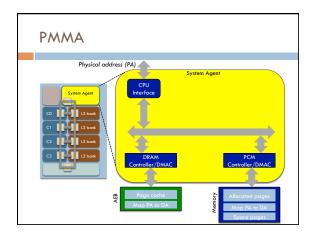
PCM Read/Write Operations □ Read ■ Writes ■ Measure resistance □ Slow bit writes: heating/ cooling: 50ns ~ 150ns Low: logic 1 (SET) High: logic 0 (RESET) Limited parallel bit writes: ■ Relatively fast large programming current □ Power efficient □ Long latency: 1000ns ■ Non-destructive □ High write energy □ Heat stress leads to failure, with limited endurance (10^7)

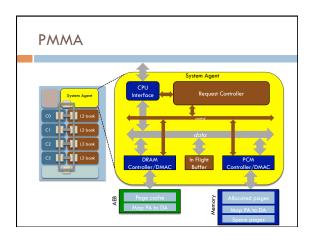
Asymmetric read/write latency and bandwidth Reads projected to reach parity with DRAM Writes will remain slow due to heating/cooling Wear-out and endurance management Integrated relatively near CPU leads to heavy usage E.g., one write/second: PCM fails in 110 days Memory will quickly fail without precautions Nonvolatility Reliability Important, desirable properties. Most focus has been on making it work first, then find ways to exploit these properties







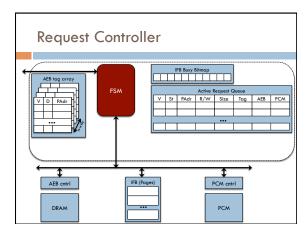


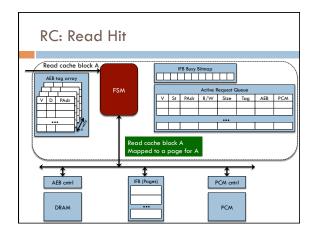


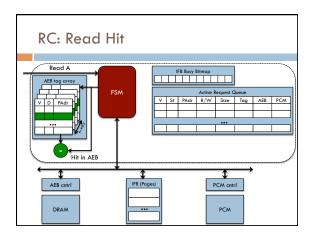
Request Controller

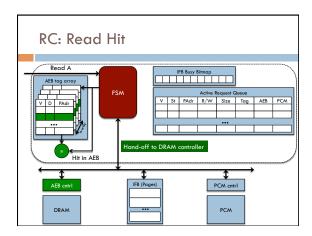
- □ Operates on pages (larger than cache block from CPU)
- □ Processes requests & allocates resources
 - Multiple outstanding requests
 - □ Page allocation & eviction (AEB)
 - Map physical to device address
- Book keeping
 - □ Track resources used, including what is cached & where
 - □ Map physical address (PA) to PCM device address (DA)
 - □ IFB: High speed memory buffers inflight pages (AEB/PCM)

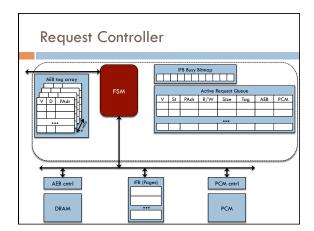
Request Controller 10/from CPU interface 15 Bury Bitmap Active Request Queue V St PAdr R/W Size Tog AEB PCM AEB Bookkeeping Request Bookkeeping

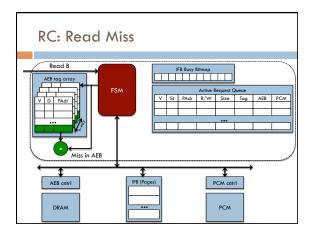


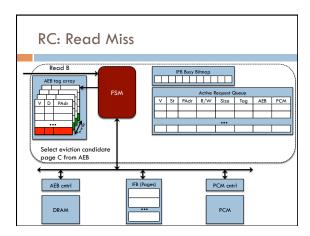


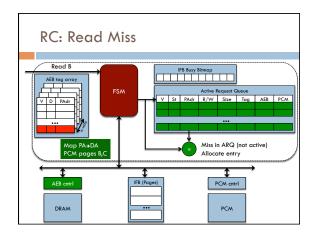


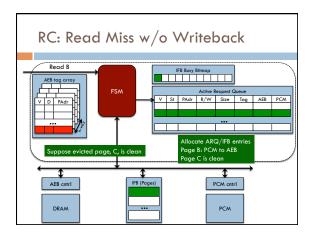


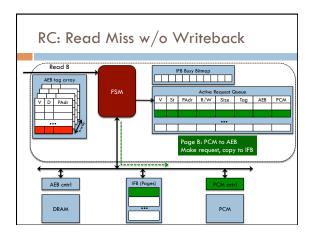


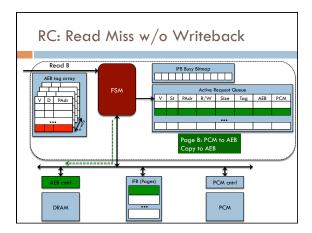


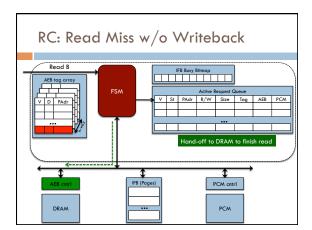


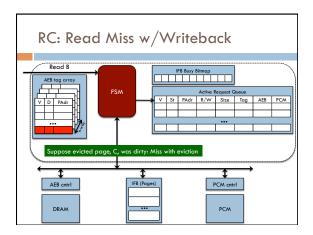


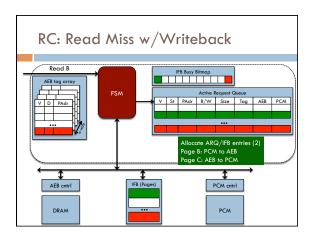


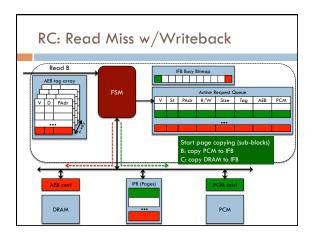


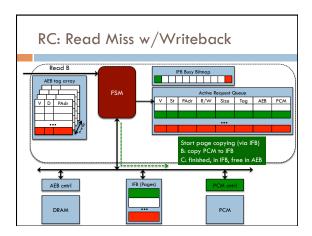


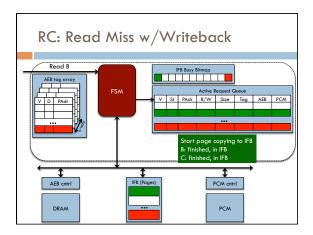


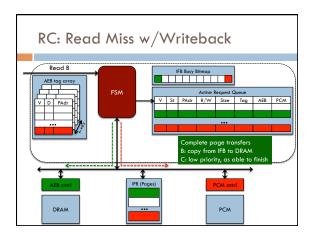


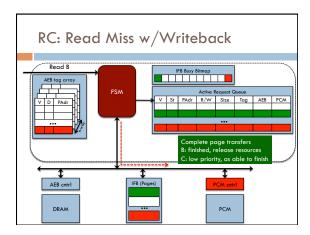


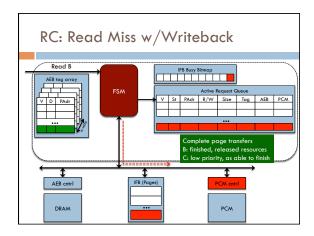


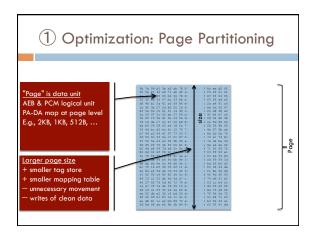


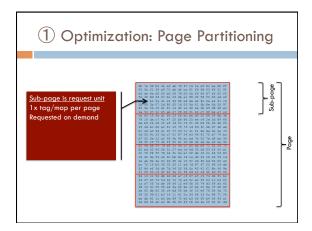


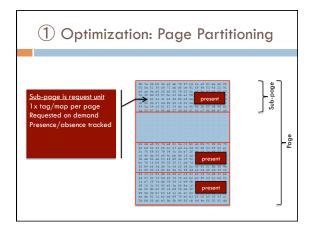


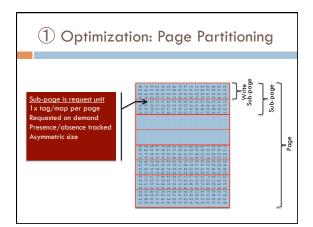


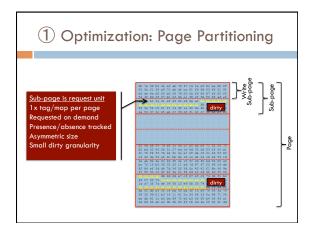


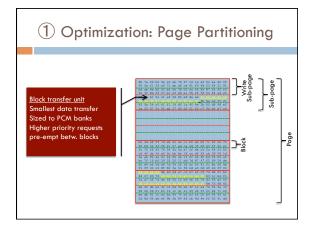


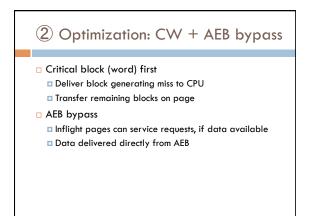


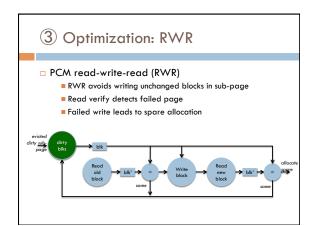


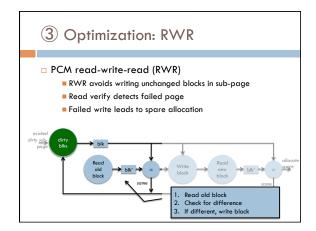


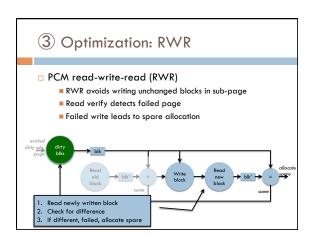




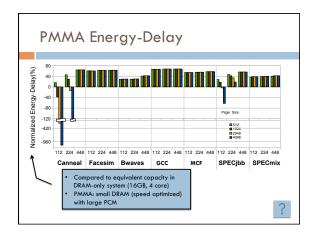


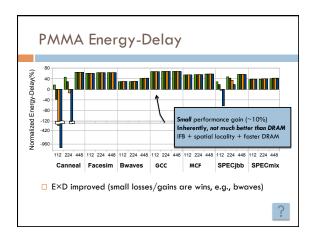


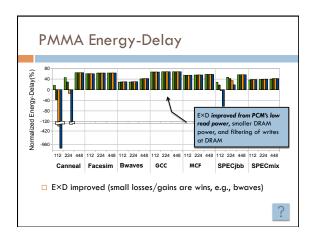


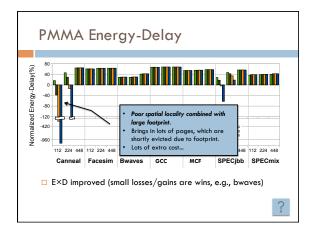


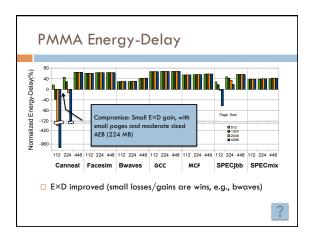
| 4 Optimization: Endurance |
|--|
| AEB eviction policy (N-chance) to minimize writes Non-uniform writes to memory Uneven writes cause pages to fail before others Failed page(s): memory is now broken Wear-leveling to uniformly distribute writes Wear pages at same level Pages will fail at approximately same time Spare capacity Replace failed pages on-demand |

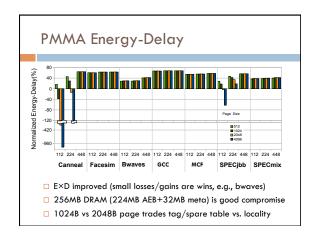


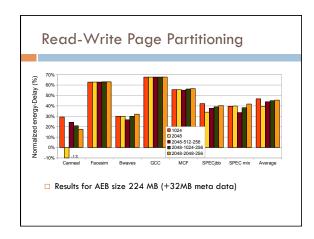


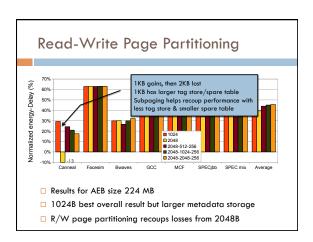


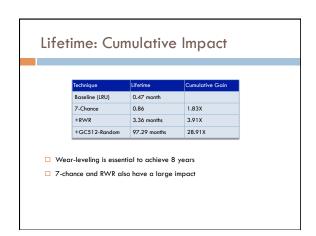












| Summary |
|--|
| □ PCM architectures □ DRAM complement for main memory? □ Flash replacement □ Memory + storage combination |
| □ Current front-runners share essential idea □ Small DRAM + Large PCM |
| Endurance on the way to being solved?Write bandwidth and energy likely to persist |